IPM - Integrated Power Module

DESCRIPTION

Fully Integrated Electronics, high current power distribution on a heavy Cu PCB, solid state microelectronics to control vehicle exterior lighting in a small packaging envelope.

BENEFITS

- Establish high speed CAN-BUS system integrated under-hood Power Distribution Center with body control functionality.
- Reduce development lead time.
- Heat & Water resistant structure.

SPECIFICATIONS

RESULTS

- Improve the flexibility of circuit design.
- Reduced number of W/H circuit leads with BUS system.
- Diagnosis possible via software interface.

For more information, contact info@us.yazaki.com

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<th>Part</th>
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<th>Cavities</th>
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<td>Fuses</td>
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<td>Relays</td>
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<td>FET</td>
<td>10-power board 11-digital board</td>
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